PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT6613915

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YI-LIN TSAI	03/11/2021
WEN-SUNG HSU	03/11/2021
I-HSUAN PENG	03/10/2021
YI-JOU LIN	03/10/2021

RECEIVING PARTY DATA

Name:	MEDIATEK INC.
Street Address:	NO. 1, DUSING 1ST RD., HSINCHU SCIENCE PARK
City:	HSINCHU CITY
State/Country:	TAIWAN
Postal Code:	30078

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17208198

CORRESPONDENCE DATA

Fax Number: (404)521-4286

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 678-483-8899

Email: dan.mcclure@mqrlaw.com

Correspondent Name: MCCLURE, QUALEY & RODACK, LLP 280 INTERSTATE NORTH CIRCLE SE Address Line 1:

SUITE 550 Address Line 2:

Address Line 4: ATLANTA, GEORGIA 30339

ATTORNEY DOCKET NUMBER:	251367-3640	
NAME OF SUBMITTER:	DANIEL R. MCCLURE	
SIGNATURE:	/Daniel R. McClure/	
DATE SIGNED:	03/22/2021	

Total Attachments: 2

source=00875589#page1.tif source=00875589#page2.tif

> **PATENT** REEL: 055669 FRAME: 0961 506567136

ASSIGNMENT

WHEKEAS	, Il-Liln i	SAI, Wen-Sung	j HSU, I-HSU	ian reng and	II-GOR PIN
		IGNOR, has/have the below identifi			
Title: SEI	1ICONDUCTOR	PACKAGE STRU	JCTURE		
Filed:	1;	S	erial No.		
	***************************************	***************************************			

WHEREAS, MediaTek Inc. of No. 1, Dusing 1st Rd., Hsinchu Science Park, Hsinchu City 30078, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, and the entire rights, title and interest in and to any and all foreign patents and applications for any invention described in said U.S. patent applications, in any and all countries foreign to the U.S., including all rights of priority arising from them, and all the rights and privileges under any and all forms of protection, including patents, that may be granted in said countries foreign to the U.S. for them, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assigner had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

Yi-Ain TSAI	>0>1/3/11
Yi-(in TSAI	Date
L-JM:	>o>1/3/1/
Wen-Sung HSÚ	Date
J- William Peng	2021 /3 /1 °
I-Hsuan PENG	Date
4 Lohi	2021/3/18

Date

Yi-Jou LIN